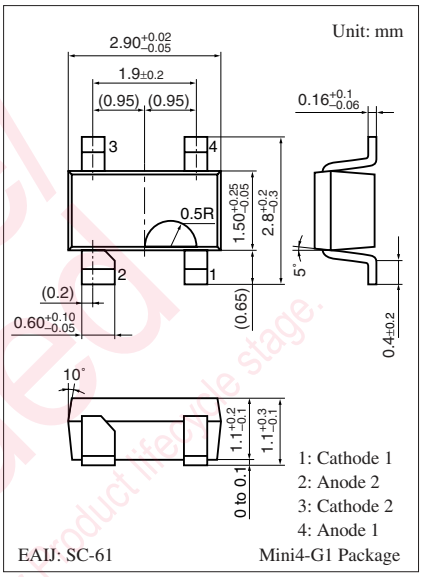
MA4X160 (MA160)

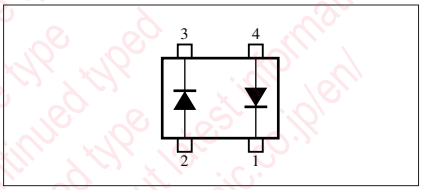
Silicon epitaxial planar type

For high-speed switching circuits



Marking Symbol: M1D

Internal Connection



■ Features

- Two isolated elements are contained in one package, allowing high-density mounting
- Centrosymmetrical wiring, allowing to free from the taping direction
- Short reverse recovery time t_{rr}
- Small terminal capacitance C_t

■ Absolute Maximum Ratings $T_a = 25°C$

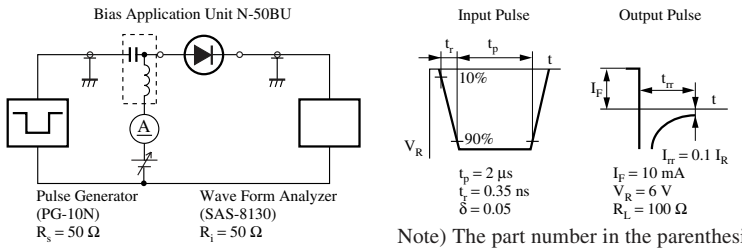
Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	40	V
Maximum peak reverse voltage		V_{RM}	40	V
Forward current (Average)	Single	$I_{F(AV)}$	100	mA
	Series		75	
Repetitive peak forward current	Single	I_{FRM}	225	mA
	Series		170	
Non-repetitive peak forward surge current *	Single	I_{FSM}	500	mA
	Series		375	
Junction temperature		T_j	150	°C
Storage temperature		T_{stg}	−55 to +150	°C

Note) *: t = 1 s

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

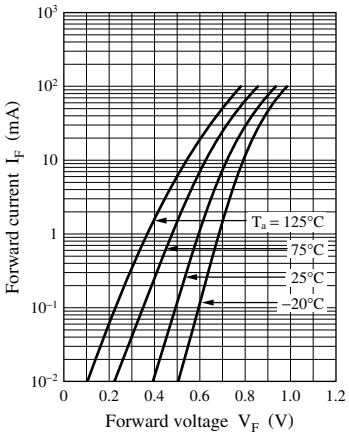
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 100 mA		0.95	1.20	V
Reverse voltage	V_R	I_R = 100 µA	40			V
Reverse current	I_R	V_R = 35 V			0.1	µA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		0.9	2.0	pF
Reverse recovery time *	t_{rr}	I_F = 10 mA, V_R = 6 V I_{rr} = 0.1 I_R , R_L = 100 Ω			3	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring method for diodes.
2. Absolute frequency of input and output is 100 MHz.
3. *: t_{rr} measurement circuit

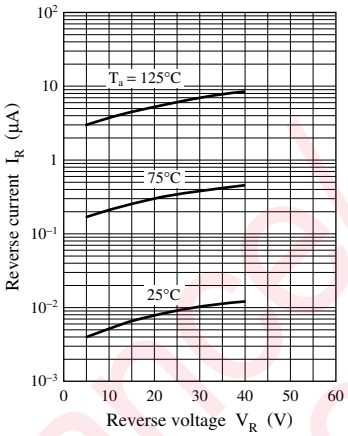


Note) The part number in the parenthesis shows conventional part number.

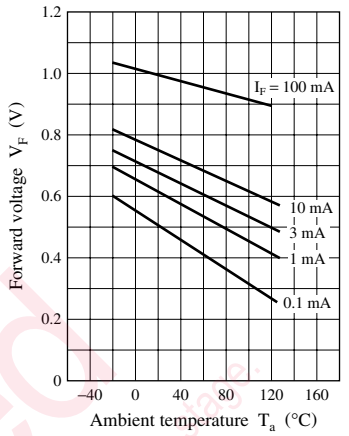
I_F — V_F



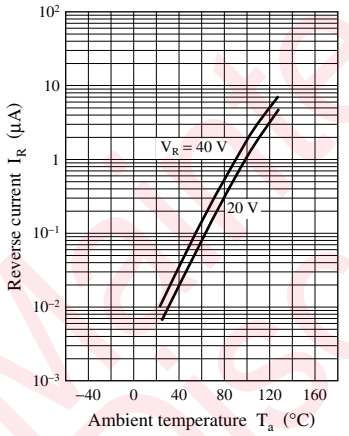
I_R — V_R



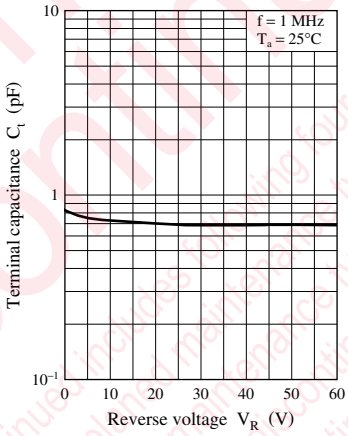
V_F — T_a



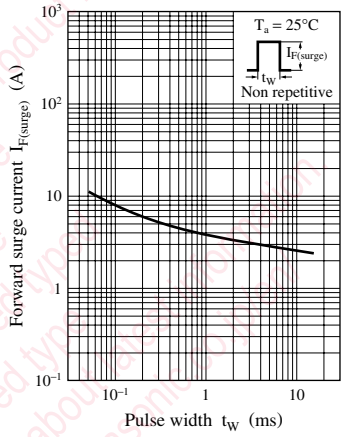
I_R — T_a



C_t — V_R



$I_{F(surge)}$ — t_W



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